

Label, White SEMIMATTE Polyimide, Permanent acrylic PS, blank, 20 x 8 mm

Drawing Number: **DK009-05-05-26** NR Revision **0 1 2 3 4 5 6 7 8 9**

Date:	05.05.2026	Print/Cut Tolerance	Thickness Tolerance	Scale
-------	------------	---------------------	---------------------	-------

SAP PN: N/A	± 0.5 mm	See Material Data Sheet	1:1
-------------	----------	-------------------------	-----

MPN: LTT-7074-S02000080001-10k-A76-001	Format A4
--	-----------




Material: LTH-7074 - Polyimide Semi-Matt White

This document can't be used or copied without authorisation from LTHD Corp. and must be treated as confidential information.
Property of LTHD Corporation.

TECHNICAL INFORMATION

Transfer Polyimide Semi-Matt White

LTH - 7074

Description	A low caliper semi-matt white polyimide film for labelling printed circuit boards, heat and chemical resistance. The high opacity white topcoat is specifically designed for thermal transfer printing and offers good scratch, scuff, high temperature and solvent resistance.		
Key Features	Very good TT printability. Very high chemical resistance of TT print.		
Construction	FACE STOCK		White semi-matt topcoated polyimide film
	ADHESIVE		High performance solvent acrylic adhesive
	RELEASE LINER		Siliconized, bleached, super-calendered liner
Facestock			
Caliper:	0,046	mm	ISO 534
Adhesive	High performance acrylic adhesive with excellent heat and chemical resistance.		
Basis weight:	27	g/m ²	
Initial Tack:	5.5	N/25 mm	FTM 9 stainless steel
Peel Adhesion:	8	N/25 mm	FTM 2 steel 24 hrs.
Min. application temperature:	+10	°C	
Min. service temperature:	-40	°C	
Max. peak temperature:	+300	°C	
Release Liner	Siliconized, bleached, super-calendered liner. Good die-cutting and matrix stripping. Suitable for roll-to-roll conversion.		
Basis weight:	80	g/m ²	ISO 536
Caliper:	0,073	mm	ISO 534
Transparency:	47	%	DIN 53147
Total construction caliper	0,145	mm	
Shelf life	From the date of manufacture one year in +22°C and RH 50%. In original packaging and protected from light.		
Peel Adhesion	180°, 300 mm/min in N/25mm. FTM1		

Surface	dwelt time 20 min	dwelt time 24 hrs
Epoxy Printed Circuit Board	4,5	7
Stainless steel	4,5	6,5

Short term high temperature resistance

The label material has been tested on Epoxy Printed Circuit Board. A typical reflow solder profile with a maximum temperature peak of 235°C/255°C has been processed. No visible changes could be noticed. Print is still legible. The printing is still legible (tested with ribbons AXR7+, AXR8, B110CR).

Chemical Resistance

Cleaning agent	Cleaner agent base	Process	Wash time	Temp. (°C)	Rinse time	Hot air drying 80(°C)	Visual apperance
Vigon US (30%) ¹	Water based	Ultrasonic	15 min	65	5 min	30 min	No change
Vigon A200 (30%) ¹	Water based	Spray-in-air	15 min	65	5 min	30 min	No change
Vigon A201 (20%) ¹	Water based	Spray-in-air	15 min	65	5 min	30 min	No change
Vigon A250 (30%) ¹	Water based	Spray-in-air	15 min	65	5 min	30 min	No change
Vigon N600 (30%) ¹	Water based	Spray-in-air	15 min	65	5 min	30 min	No change
Zestron FA ⁺	Solvent	Ultrasonic	15 min	60	5 min	30 min	No change
Zestron VD ¹	Solvent	Ultrasonic	15 min	45	Steam rinsed	Vacuum dried	No change
Atron AC205 (15%) ¹	Water based	Ultrasonic	15 min	65	5 min	30 min	No change

The performance results are based on simulation of a typical PCB cleaning process including a simulation of a solder process. Each cleaning process cycle was performed 3 times.

Thermal Transfer Printing
Printability – Physical Resistance:

Flat head printers (tests were performed with the printer Zebra XII 140):

Ribbon	Settins speed	energy	Quality print	ANSI Grade	Scratch resist.	Tape resist.
Armor AXR7+	3	30	++	A	++	+
Armor AXR8	3	25	++	A	++	+
DNP R300	6	25	++	A	++	+
DNP R510	3	30	++	A	++	+
Ricoh B110CR	3	25	++	A	++	+

ANSI (American National Standards Institute)

Grade: information about barcode quality

A: excellent B: good C: acceptable D: readable with difficulty

++: excellent +: good o: acceptable -: poor

Chemical Resistance:

The printed samples passed a simulation of a solder process, followed by typical PCB cleaning processes (3 cycles), as described above. Afterwards the evaluation took place.

	AXR7+	AXR8	R300	R510	B110CR
Atron® AC205 (15%)	+	+	+	+	+
Atron® AC207 (15%)	+	+	+	+	+
Vigon® A200 (30%)	+	+	+	+	+
Vigon® A201 (20%)	+	+	+	+	+
Vigon® A250 (30%)	+	+	+	+	+
Vigon® N600 (20%)	+	+	+	+	+
Vigon® US (30%)	+	+	+	+	+
Zestron® FA+ ¹	+	+	+	+	+
Zestron® VD ¹	+	+	+	+	+

+: good (no change) o: acceptable (minor change, still readable) -: poor

Printing and conversion

Testing is recommended to ensure satisfactory print results and chemical resistance.

Approvals

UL Recognition - This product meets the requirements as stated in UL 969 for indoor use, including thermal transfer printing.

Application and use

This polyimide label material is optimised for printing and specially formulated to withstand the high temperatures of the reflow process. It can be applied to all leaded and lead-free soldering processes in the market, but is not recommended for wave solder applications when applied to the bottom side of the PCB.

The specially designed topcoat in combination with the appropriate thermal transfer ribbon features excellent scuff, scratch high temperature and solvent resistance.

Disclaimer

All data to be considered as typical values and subject to change without prior notice. Further testing is always recommended.

All statements, technical information, and recommendations related to LTHD's products are based on information believed to be reliable, but the accuracy or completeness is not guaranteed. Before using this product, you must evaluate it and determine if it is suitable for your intended application. You assume all risks and liability associated with such use.